

CS FINISH Sandwich Pad C30

Polishing Pad

09/2014

:: CHARACTERISTIC

The **CS FINISH Sandwich Pad C30** can be used to polish out holograms, as well as medium to light scratches. The black intermediate layer provides added stability and even removal during polishing.

:: AREA OF APPLICATION

The Pad works best with the **CS POLISH C-30**.

:: PRODUCT DATA

MATERIAL DATA

Density:	36-41 kg/m ³
Tensile Strength:	>200 kPa
Elongation:	>250 %
Hardness:	8-11 kPa
Cell qty.:	16 ppi

SAFETY ISSUES

The before mentioned technical data and information, especially the recommendations for applying and using our products, are based on our current knowledge and experience when applied under normal conditions. In practice, the materials, surfaces or site conditions are so different that no warranty regarding the working results or liability, arising out of any relationship, can be inferred neither from this information nor from a verbal consultation, except we are charged with intent or gross negligence. In this case the user is obliged to prove that he has informed us about all points required for a proper and promising judgement in writing, in time and completely. Patent rights of any third party are to be observed. Furthermore, our general sales and delivery Terms and Conditions and the latest Technical Data Sheet, which should be demanded, apply.



Directions for handling and waste disposal are in our Material Safety Data Sheet and the specifications of the Employers Liability Insurance Association for the chemical industry.

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